

In the Claims

Please amend the claims as follows.

Kindly cancel claims 18-25, without prejudice.

1. (Original) A carrier for a semiconductor die comprising:
 - a substrate having a cavity formed in said substrate, said cavity having a bottom and sidewalls, said sidewalls having a stepped tier;
 - a plurality of electrically conductive contacts on an underside of said substrate;
 - a plurality of electrically conductive tabs disposed on said stepped tier;
 - a plurality of electrically conductive external bond terminals disposed on an edge of said substrate; and
 - a plurality of electrically conductive paths formed in said substrate and electrically coupled between said electrically conductive tabs, said electrically conductive contacts, and said electrically conductive external bond terminals.
2. (Original) A carrier for a semiconductor die as in claim 1, wherein said substrate is formed from a multilayer of ceramic substrates.
3. (Original) A carrier for a semiconductor die as in claim 1, wherein said substrate is formed from laminates of organic dielectrics.
4. (Original) A carrier for a semiconductor die as in claim 1, wherein said substrate is formed from deposited thin film layers.

5. (Original) A carrier for a semiconductor die as in claim 1 further including a sealing lid disposed on said substrate and covering said cavity.

6. (Original) A carrier for a semiconductor die as in claim 1 further including a plurality of wires electrically coupled between the semiconductor die and the plurality of electrically conductive tabs.

7. (Original) A carrier for a semiconductor die as in claim 1 wherein said plurality of electrically conductive external bond terminals disposed on an edge of said substrate are disposed on a ledge in a recess formed in said edge of said substrate.

8. (Original) A carrier for a semiconductor die as in claim 1 wherein said plurality of electrically conductive paths are formed from conductive vias and conductive lines in said substrate.

9. (Original) A carrier for a semiconductor die as in claim 1 wherein said sidewalls have a plurality of stepped tiers and said plurality of electrically conductive tabs are disposed on said plurality of stepped tiers.

10. (Original) A carrier for a semiconductor die comprising:
a substrate having an upper surface and a lower surface;
a plurality of electrically conductive surface contacts disposed on said upper surface of said substrate;
a plurality of electrically conductive contacts on an underside of said substrate;

a plurality of electrically conductive external bond terminals disposed on an edge of said substrate; and

a plurality of electrically conductive paths formed in said substrate and electrically coupled between said electrically conductive surface contacts, said electrically conductive contacts, and said electrically conductive external bond terminals.

11. (Original) A carrier for a semiconductor die as in claim 10, wherein said substrate is formed from a multilayer of ceramic substrates.

12. (Original) A carrier for a semiconductor die as in claim 10, wherein said substrate is formed from laminates of organic dielectrics.

13. (Original) A carrier for a semiconductor die as in claim 10, wherein said substrate is formed from deposited thin film layers.

14. (Original) A carrier for a semiconductor die as in claim 10 further including a cover disposed on said substrate and covering the semiconductor die.

15. (Original) A carrier for a semiconductor die as in claim 10 wherein the semiconductor die has a plurality of semiconductor die contacts electrically connected to said plurality of electrically conductive surface contacts.

16. (Original) A carrier for a semiconductor die as in claim 10 wherein said plurality of electrically conductive external bond terminals disposed on an edge of said substrate are disposed on a ledge in a recess formed in said edge of said substrate.

17. (Original) A carrier for a semiconductor die as in claim 10 wherein said plurality of electrically conductive paths are formed from conductive vias and conductive lines in said substrate.

18. (Canceled)

19. (Canceled)

20. (Canceled)

21. (Canceled)

22. (Canceled)

23. (Canceled)

24. (Canceled)

25. (Canceled)